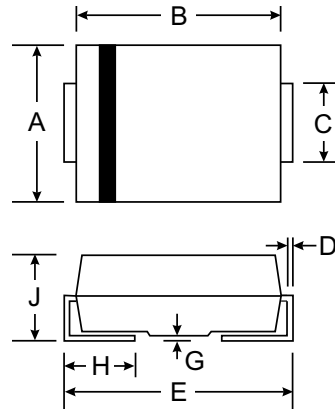


Features

- For Surface Mounted Applications
- High Temperature Metallurgically Bonded Contacts
- Capable of Meeting Environmental Standards of MIL-STD-19500
- Plastic Material - UL Flammability Classification 94V-0
- High Reliability
- Submersible Temperature of 265°C for 10 Seconds in Solder Bath
- Glass Passivated Junction



| SMB - DO-214AA | | |
|----------------------|------|------|
| Dim | Min | Max |
| A | 3.30 | 3.94 |
| B | 4.00 | 4.65 |
| C | 1.95 | 2.21 |
| D | 0.15 | 0.40 |
| E | 5.00 | 6.00 |
| G | 0.10 | 0.20 |
| H | 0.76 | 1.52 |
| J | 2.00 | 2.62 |
| All Dimensions in mm | | |

Mechanical Data

- Case: SMB, Molded Plastic
- Terminals: Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Approx. Weight: 0.093 grams
- Mounting Position: Any

Maximum Ratings and Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.
Single phase, half wave, 60Hz resistive or inductive load.

| Characteristic | Unit | FR1A | FR1B | FR1D | FR1G | FR1J | FR1K | FR1M | Unit |
|---|-----------------|-------------|------|------|------|------|------|------|--------------------|
| Maximum Recurrent Peak Reverse Voltage | V_{RRM} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum RMS Voltage | V_{RMS} | 35 | 70 | 140 | 280 | 420 | 560 | 700 | V |
| Maximum DC Blocking Voltage | V_{DC} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum Average Forward Rectified Current @ $T_A = 75^\circ\text{C}$ | $I_{(AV)}$ | 1.0 | | | | | | | A |
| Peak Forward Surge Current 8.3 ms single half sine-wave superimposed on rated load (JEDEC Method) | I_{FSM} | 30 | | | | | | | A |
| Maximum Instantaneous Forward Voltage at 1.0 A | V_F | 1.3 | | | | | | | V |
| Maximum DC Reverse Current at Rated DC Blocking Voltage @ $T_A = 25^\circ\text{C}$ @ $T_A = 125^\circ\text{C}$ | I_R | 5.0 | | | | | | | μA |
| | | 100 | | | | | | | |
| Maximum Full Load Reverse Current Full Cycle Average @ $T_A = 75^\circ\text{C}$ | | 50 | | | | | | | μA |
| Maximum Reverse Recovery Time (See Note 1) | t_{rr} | 150 | | | | 250 | 500 | 500 | ns |
| Maximum Thermal Resistance (See Note 2) | $R_{\theta JL}$ | 30 | | | | | | | $^\circ\text{C/W}$ |
| Typical Junction Capacitance (See Note 3) | C_J | 15 | | | | | | | pF |
| Operating and Storage Temperature Rating | T_J, T_{STG} | -65 to +175 | | | | | | | $^\circ\text{C}$ |

- Notes:
1. Reverse Recovery Test Conditions: $I_F = 0.5\text{A}$, $I_R = 1\text{A}$, $I_{RR} = 0.25\text{A}$
 2. Thermal Resistance from junction to lead with 6.0mm² copper pads
 3. Measured at 1.0MHz and applied reverse voltage of 4.0V

